

N-Channel 600-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$ (Typ.)	I _D (A) ^a	Q _g (Typ.)			
600	25 at V _{GS} = 10 V	0.12	3.6 nC			

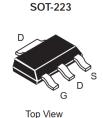
FEATURES

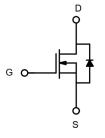
- Depletion mode MOSFET
- 100 % R_g Tested
- Low Gate Charge



APPLICATIONS

· Load Switch





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted							
Parameter	Symbol	Limit	Unit				
Drain-Source Voltage	V _{DS}	600	V				
Gate-Source Voltage		V_{GS}	± 30]			
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	- I _D	0.12 ^{b, c}	A			
Continuous Drain Current (1) = 150 C)	T _A = 70 °C		0.10 ^{b, c}				
Pulsed Drain Current	T _A = 25 °C	I _{DM}	0.48] ^			
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	0.12 ^{b, c}				
Avalanche Current	L = 0.1 mH	I _{AS}	0.1				
Single-Pulse Avalanche Energy	L = 0.1 IIII1	E _{AS}	0.1	mJ			
	T _C = 25 °C	P _D	2.5	W			
Maximum Power Dissipation	$T_C = 70 ^{\circ}C$		1.9				
Maximum Tower Dissipation	$T_A = 25 ^{\circ}C$		1.86 ^{b, c}				
	T _A = 70 °C		0.7 ^{b, c}				
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	≤ 5 s	R _{thJA}	90	115	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	60	75	C/ VV	

Notes:

- a. Based on T_C = 25 °C. b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under Steady State conditions is 120 °C/W.



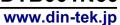


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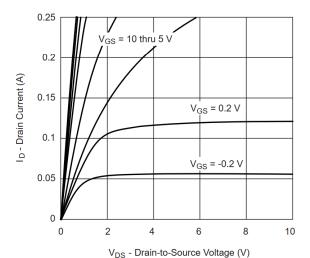
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					<u>'</u>		
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	600			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L = 250 · A		0.6		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 1.5		11107 C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 100 \mu A$	-2.5		-1	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = 20 \text{ V}$			100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}$	20			mA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	0.1			Α	
Dunin Course On State Besistance	R _{DS(on)}	V _{GS} = 0 V, I _D = 0.01 A		30	60	Ω	
Drain-Source On-State Resistance ^a	(On)	V _{GS} = 10 V, I _D = 0.1 A		25	45		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 5V, I _D = 0.1 A		0.15		S	
Dynamic ^b				,			
Input Capacitance	C _{iss}			96		pF	
Output Capacitance	C _{oss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		7.5			
Reverse Transfer Capacitance	C _{rss}			3.3			
Total Gate Charge	Qg			3.6		nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 300 \text{ V}, V_{GS} = -3 \text{ to } 5 \text{ V},$ $ID = 0.1 \text{ A}$		0.2			
Gate-Drain Charge	Q _{gd}	10 - 0.1 A		2			
Gate Resistance	R_g	f = 1 MHz		4.5		Ω	
Turn-On Delay Time	t _{d(on)}			6			
Rise Time	t _r	$V_{DD} = 300 \text{ V}, I_{D} = 0.1 \text{ A},$		20		ns	
Turn-Off Delay Time	t _{d(off)}	V_{GEN} = -3 to 5 V, R_G = 15 Ω		10			
Fall Time	t _f			25		1	
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			0.12	A	
Pulse Diode Forward Current ^a	I _{SM}				0.48	^	
Body Diode Voltage	V _{SD}	I _S = 0.2 A			1.5	V	
Body Diode Reverse Recovery Time	t _{rr}			195		ns	
ody Diode Reverse Recovery Charge Q _{rr}		I _F = 0.2 A, dl/dt = 100 A/μs, T _J = 25 °C		610		nC	
Reverse Recovery Fall Time	t _a	i _F = 0.2 A, αι/αι = 100 A/μs, 1 _J = 25 C		8			
Reverse Recovery Rise Time	t _b			9		ns	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

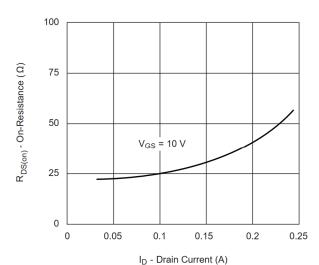
Notes: a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.



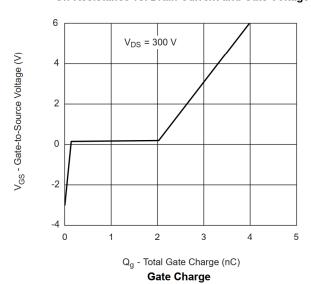
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

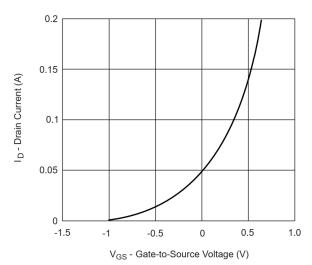


Output Characteristics

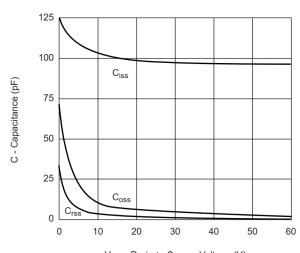


On-Resistance vs. Drain Current and Gate Voltage

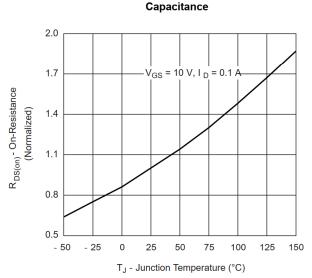




Transfer Characteristics



V_{DS} - Drain-to-Source Voltage (V)

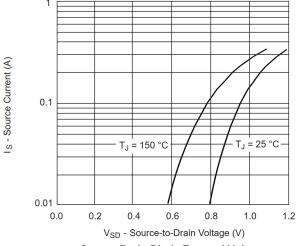


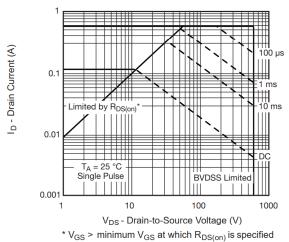
On-Resistance vs. Junction Temperature





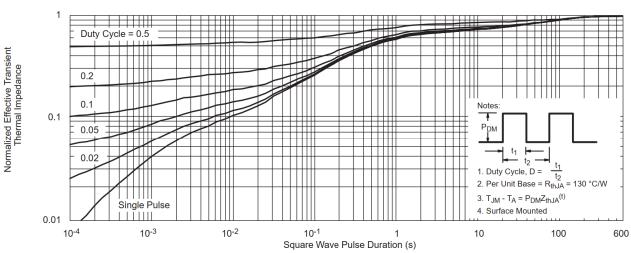
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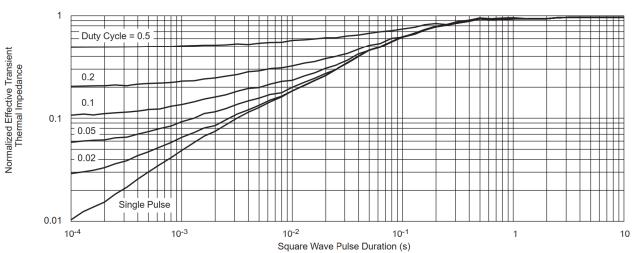


Source-Drain Diode Forward Voltage





Normalized Thermal Transient Impedance, Junction-to-Ambient

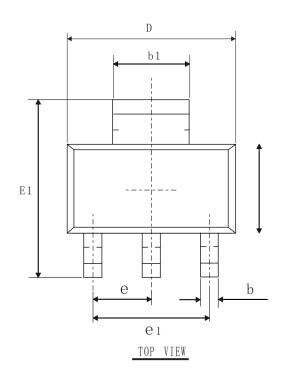


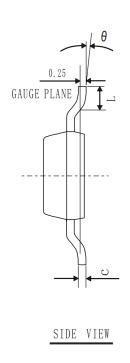
Normalized Thermal Transient Impedance, Junction-to-Foot

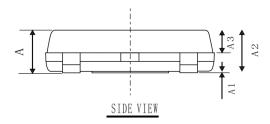




SOT-223-3L PACKAGE OUTLINE







$\begin{array}{c} \text{COMMON DIMENSIONS} \\ \text{(UNITS OF MEASURE=MILLIMETER)} \end{array}$

SYMBOL	MIN	TYP	MAX
Α	-	-	1.95
A1	0.00	0.05	0.16
A2	1.35	1.60	1.85
A3	0.65	0.90	1.15
b	0.55	0.70	0.90
b1	2.75	3.00	3.30
С	0.18	0.30	0.42
D	6.00	6.50	7.00
E	3.10	3.50	3.90
E1	6.50	7.00	7.50
e1	4.20	4.60	5.00
L	0.78	-	1.28
θ	0°	5°	10°
е	2.3BSC		
•	•	•	•





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